



FIG. 1A

(Conventional)

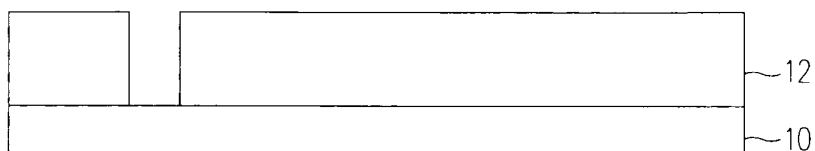


FIG. 1B

(Conventional)

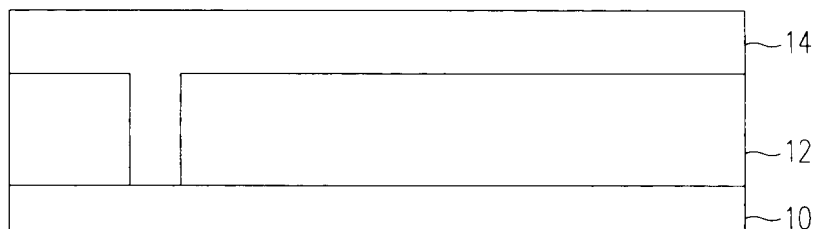


FIG. 1C

(Conventional)

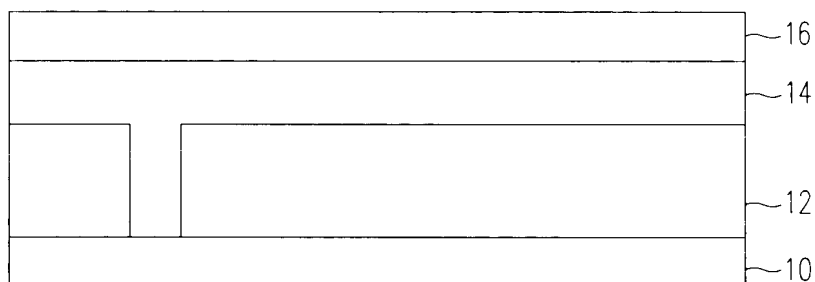


FIG. 1D

(Conventional)

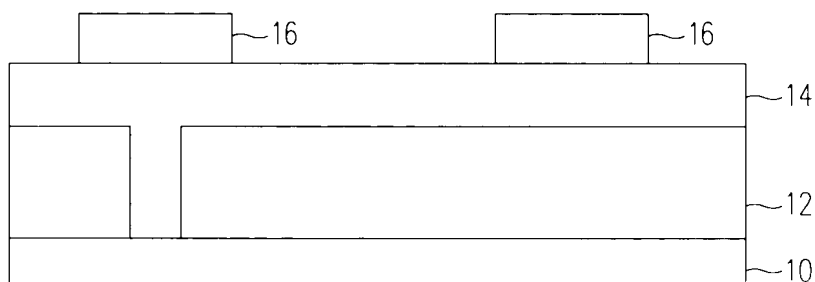


FIG. 1E

(Conventional)

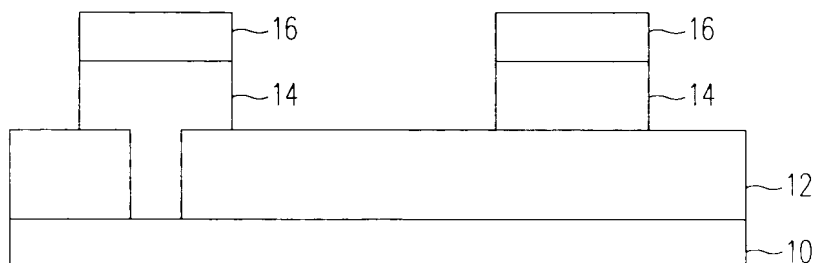




FIG. 1F
(Conventional)

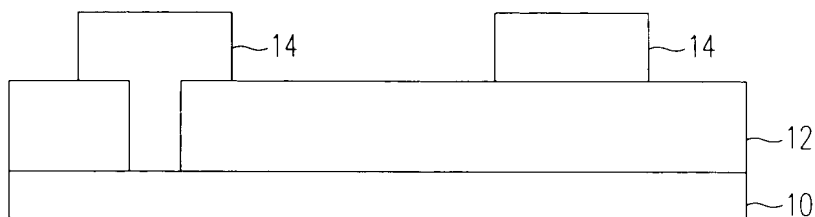


FIG. 1G
(Conventional)

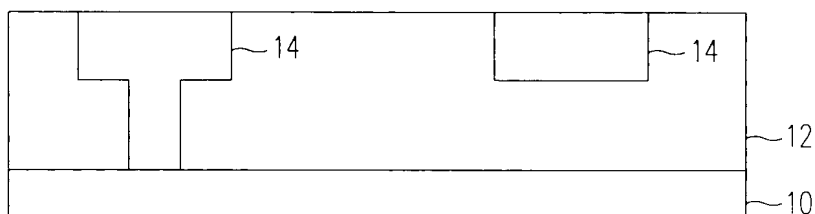


FIG. 2A
(Conventional)

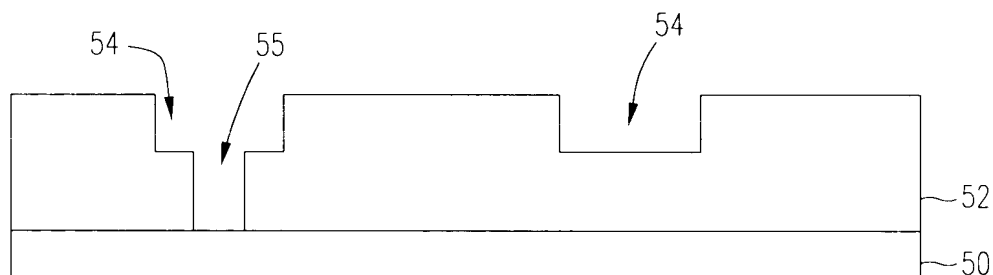


FIG. 2B
(Conventional)

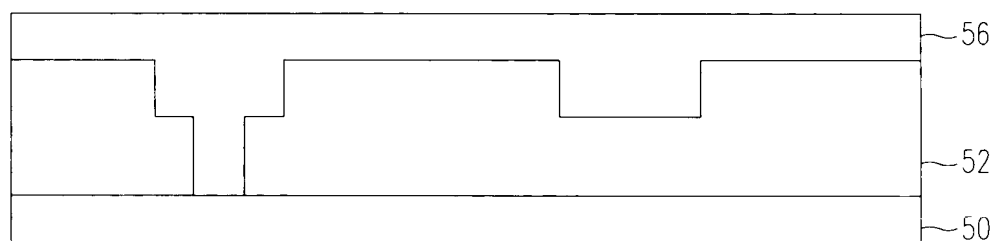
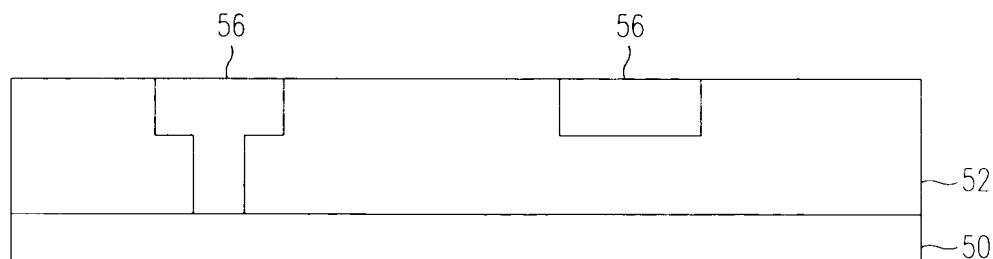


FIG. 2C
(Conventional)



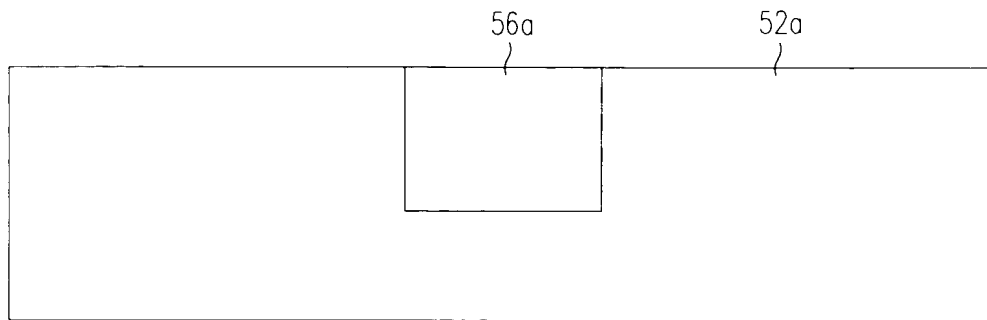


FIG. 3

(Conventional)

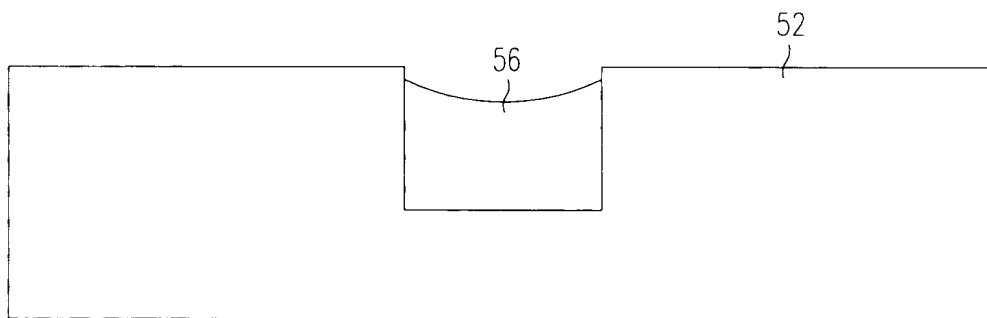


FIG. 4

(Conventional)

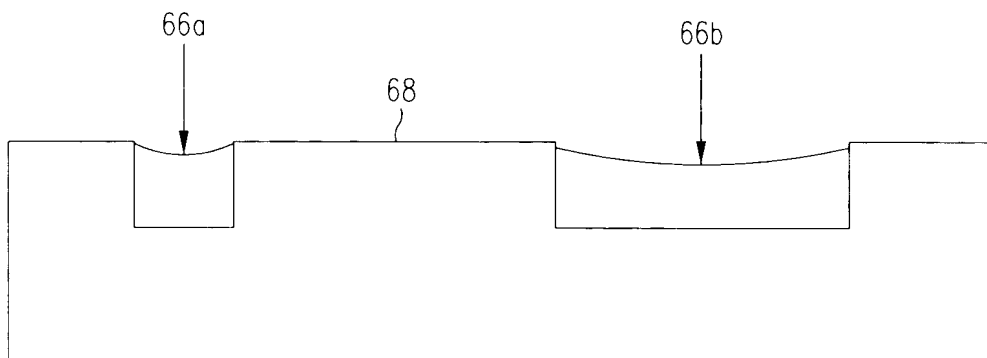


FIG. 5

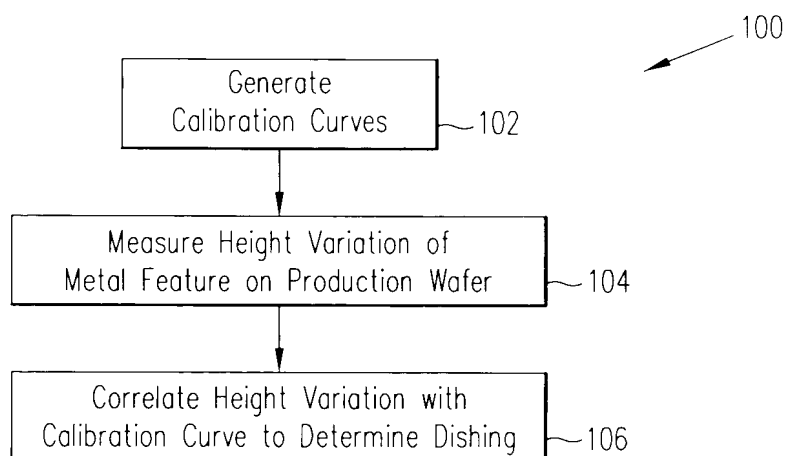


FIG. 6

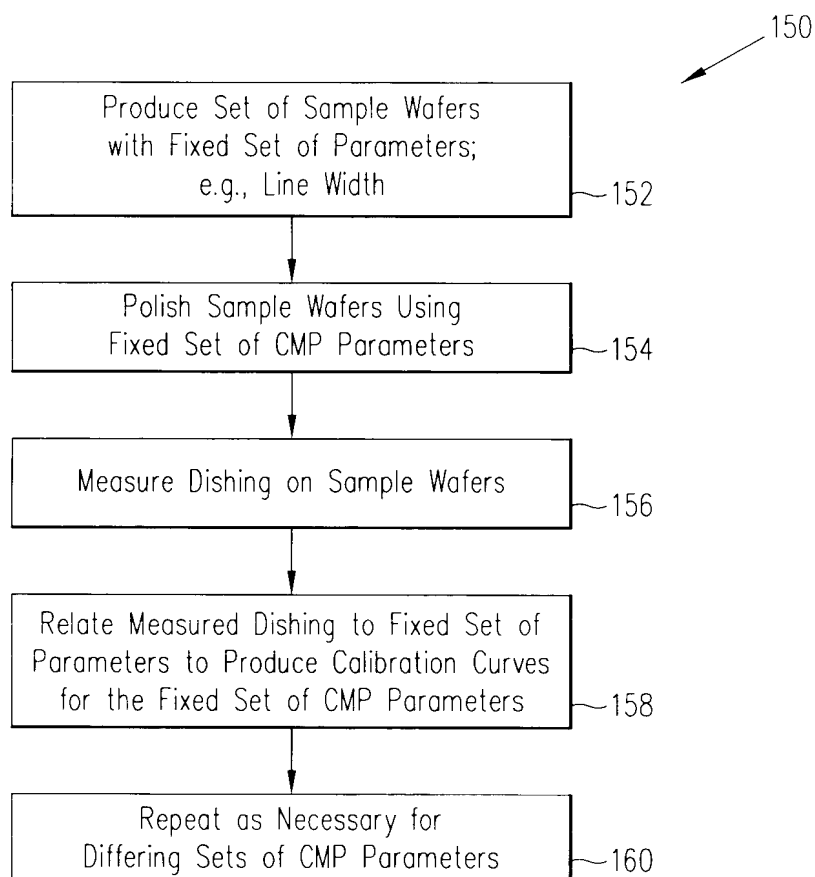
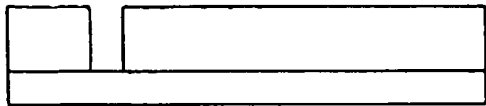
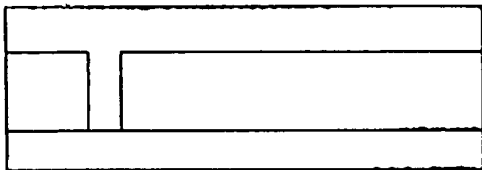


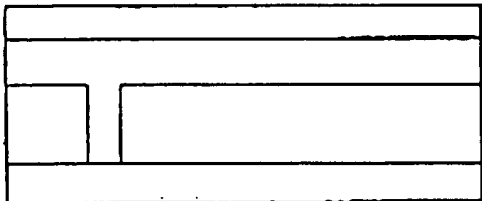
FIG. 7



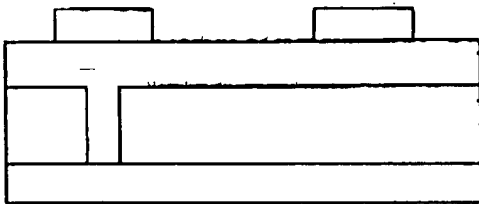
PATTERNED AND ETCHED DIELECTRI



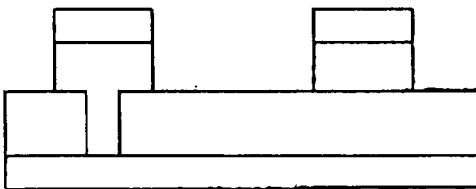
ALUMINUM DEPOSITION



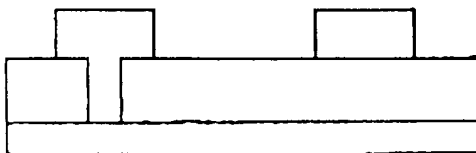
PHOTORESIST DEPOSITION



EXPOSURE AND DEVELOP

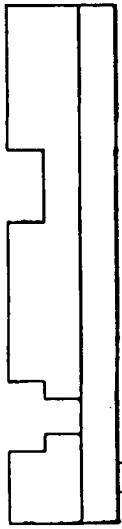


ALUMINUM ETCHING

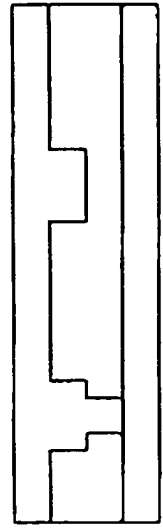


PHOTORESIST REMOVAL

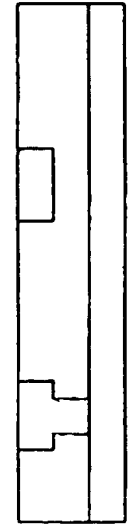
FIGURE 1



PATTERNED AND ETCHED DIELECTRIC



DIFFUSION BARRIER, NUCLEATION
LAYER AND COPPER DEPOSITION



COPPER, NUCLEATION LAYER AND
DIFFUSION BARRIER CMP

FIGURE 2

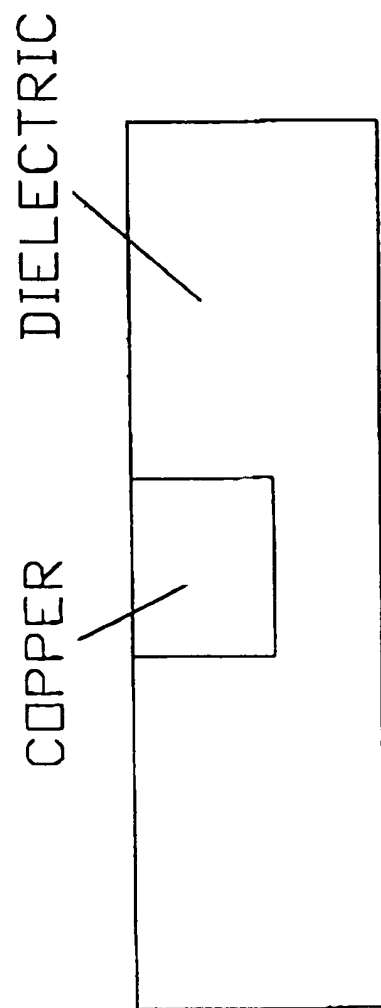


FIGURE 3

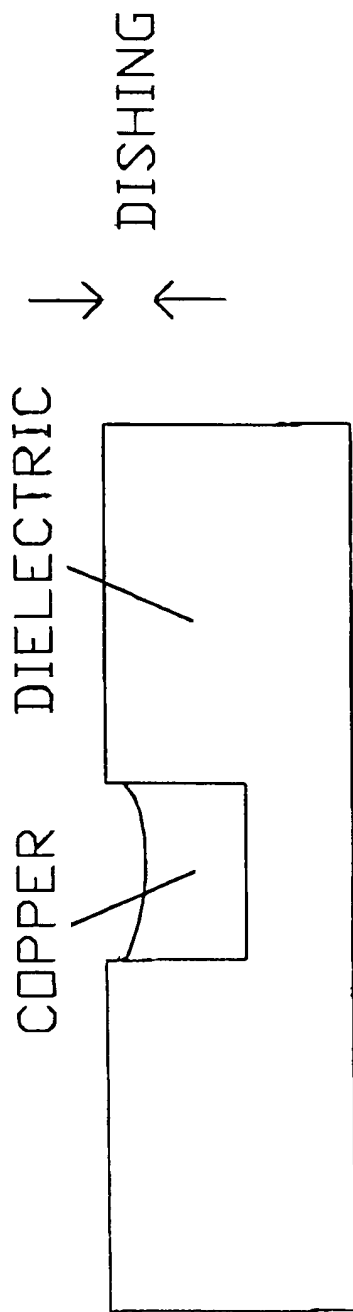


FIGURE 4

OIPF
OCT 1 6 2002
PATENT & TRADEMARK OFFICE

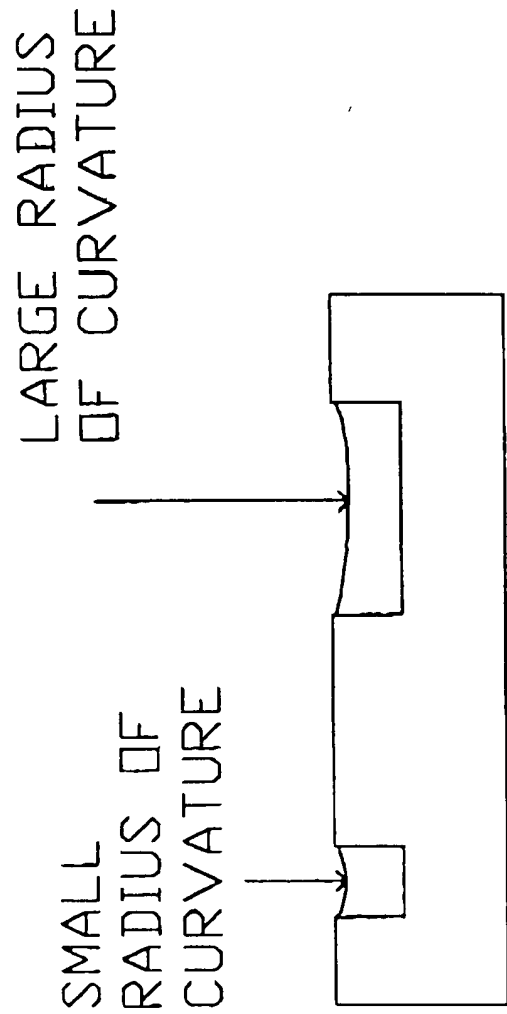


FIGURE 5